This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

- 1. (currently amended) A <u>directional</u> coupler comprising:
- a) a substrate having a plurality of layers;
- b) a film resistor formed on one of the a top layers;
- c) a capacitor formed between two of the layers;
- d) a ground plane formed on one of the layers;
- e) a transformer attached to the substrate top layer over the resistor, and the transformer electrically connected to the resistor and capacitor; and
- f) a plurality of vias extending between the layers for providing electrical connections between the resistor, capacitor, ground plane and transformer.
- (original) The coupler according to claim 1 wherein the substrate is formed from layers of low temperature co-fired ceramic.
- 3. (currently amended) The coupler according to claim 1 wherein the transformer has a binocular core having a first leg, a second leg and a third leg, and a plurality of windings a first winding wound on the first leg and a second winding wound on the third leg, the windings wound so as to directionally couple a plurality of ports.

- 4. (currently amended) The coupler according to claim 3 1 wherein an overglaze covers the resistor, the overglaze located between the resistor and the transformer the transformer is attached to the substrate using an epoxy.
- 5. (original) The coupler according to claim 4 wherein a plurality of terminals are located on an upper layer.
- 6. (original) The coupler according to claim 5 wherein the windings are electrically connected to the terminals by a plurality of welds.
- 7. (original) The coupler according to claim 1 wherein the substrate is connected to a printed circuit board by a reflowed solder paste attached to at least one terminal on a bottom layer.
- 8. (original) The coupler according to claim 1 wherein the capacitor has one electrode formed on one layer and a ground plane formed on another layer.

- 9. (currently amended) A coupler for providing coupling between an input port and a coupled port, the coupler having an output port and a terminated port, the coupler comprising:
- a) a multi-layered low temperature co-fired ceramic substrate, the substrate having a top surface and a bottom surface;
- b) a plurality of first terminals located on the top surface and a plurality of second terminals located on the bottom surface;
- c) a transformer attached to the upper top surface and electrically connected to the first terminals; and
- d) a plurality of vias extending through the substrate for providing an electrical connection between the first terminals and the second terminals; and
- e) a resistor formed on the top surface, under the transformer, the resistor electrically connected with the transformer.
- 10. (currently amended). The coupler according to claim 9 wherein an overglaze covers the resistor in order to protect the resistor from contacting the transformer is formed on the top surface and is electrically connected between the transformer and a ground.

- 11. (currently amended) The coupler according to claim 10- 9 wherein a capacitor is formed on in the substrate and is electrically connected between the transformer and a ground.
- 12. (original) The coupler according to claim 11 wherein a ground plane is formed on the substrate and is electrically connected between the transformer and a ground.
- 13. (currently amended) The coupler according to claim 11 9 wherein the transformer has a binocular core and a plurality of windings.
- 14. (original) The coupler according to claim 12 wherein the transformer is attached to the substrate using an epoxy.
- 15. (original) The coupler according to claim 14 wherein the windings are electrically connected to the first terminals by a plurality of welds.
- 16. (original) The coupler according to claim 9 wherein the substrate is connected to a printed circuit board by a reflowed solder paste attached to the second terminals on the bottom surface.

17.	(original)	The coupler according to claim 11 wherein the capacitor is formed by an
elect	trode and	a ground plane having a layer of the low temperature co-fired ceramic
there	ebetween,	the electrode and the ground plane each connected to a via.

- 18. (previously withdrawn) A method of manufacturing a coupler comprising the steps of:
- a) providing a plurality of layers of low temperature co-fired ceramic;
- b) punching a plurality of holes in the low temperature co-fired ceramic layers;
- c) filling the holes with a conductive material to form a plurality of vias;
- d) screening a plurality of circuit features onto the layers;
- e) stacking the layers;
- f) firing the stacked layers in an oven to form a unitary substrate; and
- g) attaching a transformer to the substrate.
- 19. (previously withdrawn) The method according to claim 18 wherein the circuit features are chosen from the group consisting of:
- a) resistors;
- b) capacitors;
- c) circuit lines;
- d) ground planes;
- e) terminals; and
- f) resistor overglaze.

- 20. (previously withdrawn) The method according to claim 18 wherein the transformer has a plurality of wire windings, the wire windings being welded to the terminals.
- 21. (previously withdrawn) The method according to claim 18 wherein the transformer is attached to the substrate using an adhesive.
- 22. (previously withdrawn) The method according to claim 18 wherein the transformer has a binocular core, the windings wound around the core so as to form an input port, a coupled port, an output port and a terminated port.
- 23. (previously withdrawn) The method according to claim 18 wherein the substrate is attached to a printed circuit board, further comprising the steps of:
- a) screening a solder paste onto a bottom surface terminal;
- b) placing the substrate onto the printed circuit board; and
- c) reflowing the solder paste such that the substrate is attached to the printed circuit board.

- 24. (currently amended) A coupler comprising:
- a) an input port, a coupled port, an output port and a terminated port;
- b) a resistor connected to the terminated port;
- c) a capacitor connected to the terminated port;
- d) a low temperature co-fired ceramic substrate <u>having a plurality of layers</u>, the resistor <u>formed on a first layer</u> and <u>the</u> capacitor being formed on the substrate; and
- e) a transformer attached to the substrate and electrically connected to the ports;
- g) a plurality of vias extending through the substrate for providing an electrical
 connection between the transformer, the resistor, the capacitor and the ports.
- 25. 27. (canceled).
- 28. (original) The coupler according to claim 26 wherein the capacitor is formed on a second layer.
- 29. (currently amended) The coupler according to claim 26 <u>24</u> wherein a ground plane is formed on a third layer.
- 30. (currently amended) The coupler according to claim 27 24 wherein the transformer is electrically attached to a plurality of upper terminals on the first layer.

- 31. (original) The coupler according to claim 29 wherein a plurality of bottom terminals are formed on the third layer.
- 32. (original) The coupler according to claim 31 wherein the bottom terminals are connected to a printed circuit board.
- 33. (currently amended) The coupler according to claim 31 24 wherein the transformer has a binocular core and a plurality of windings.
- 34. (canceled).
- 35. (currently amended) The coupler according to claim 34 <u>24</u> wherein an epoxy is located between the resistor overglaze and the transformer, the epoxy mechanically retaining the transformer to the first layer.